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(12) **United States Design Patent**  
**Inagaki et al.**

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(54) **HEATSINK**

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(\*\*) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/179**

(58) **Field of Classification Search**  
USPC ..... D13/179, 182; D23/231; D14/230  
CPC . H01Q 1/428; H01Q 1/02; H01Q 1/38; H01L 23/367; H01L 23/3672; H05K 7/20254; F28F 3/022; F28F 3/04; F28F 21/065; G02B 1/111; F28D 15/0275  
See application file for complete search history.

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(57) **CLAIM**

We claim the ornamental design for a heatsink, as shown and described.

**DESCRIPTION**

FIG. 1 shows a top isometric view of a heatsink in accordance with the present design.

FIG. 2 shows a bottom isometric view of the heatsink in FIG. 1.

FIG. 3 shows a top view of the heatsink in FIG. 1.

FIG. 4 shows a bottom view of the heatsink in FIG. 1.

FIG. 5 shows a right side view of the heatsink in FIG. 1.

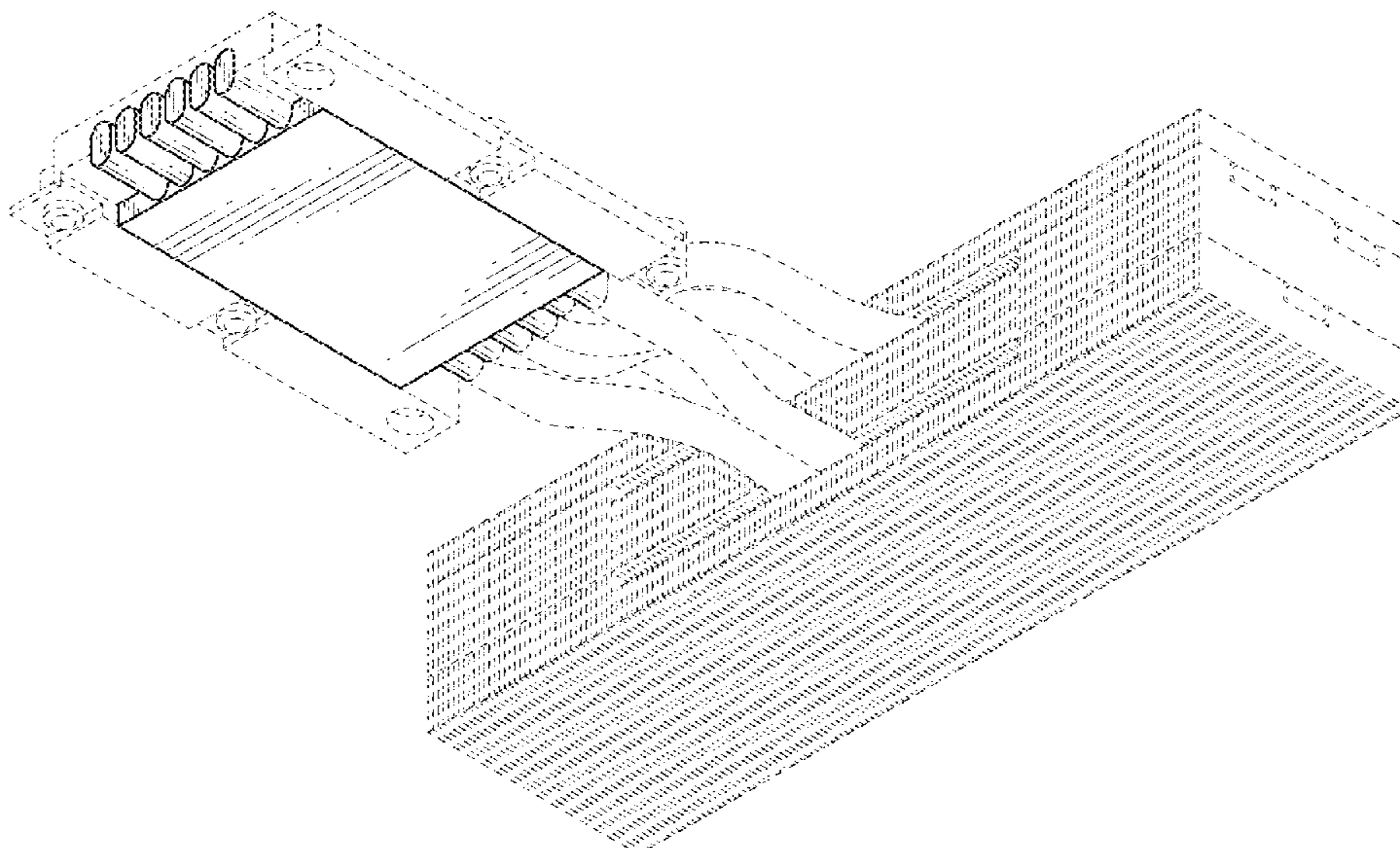
FIG. 6 shows a left side view of the heatsink in FIG. 1.

FIG. 7 shows a front view of the heatsink in FIG. 1; and,

FIG. 8 shows a rear view of the heatsink in FIG. 1.

The even broken lines illustrate environment and form no part of the claimed design. The dot-dash broken lines represent boundary lines and form no part of the claimed design.

**1 Claim, 6 Drawing Sheets**



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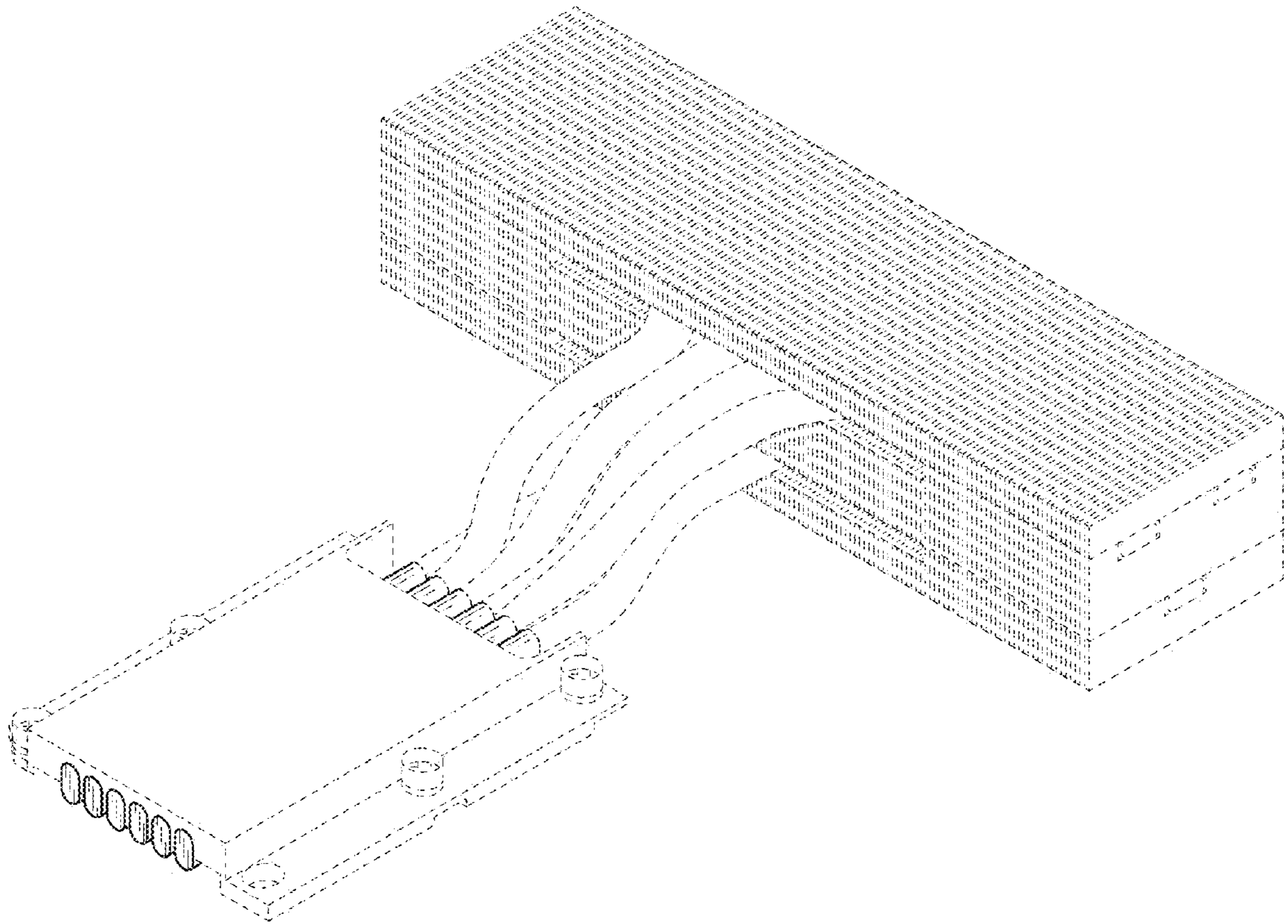


FIG. 1

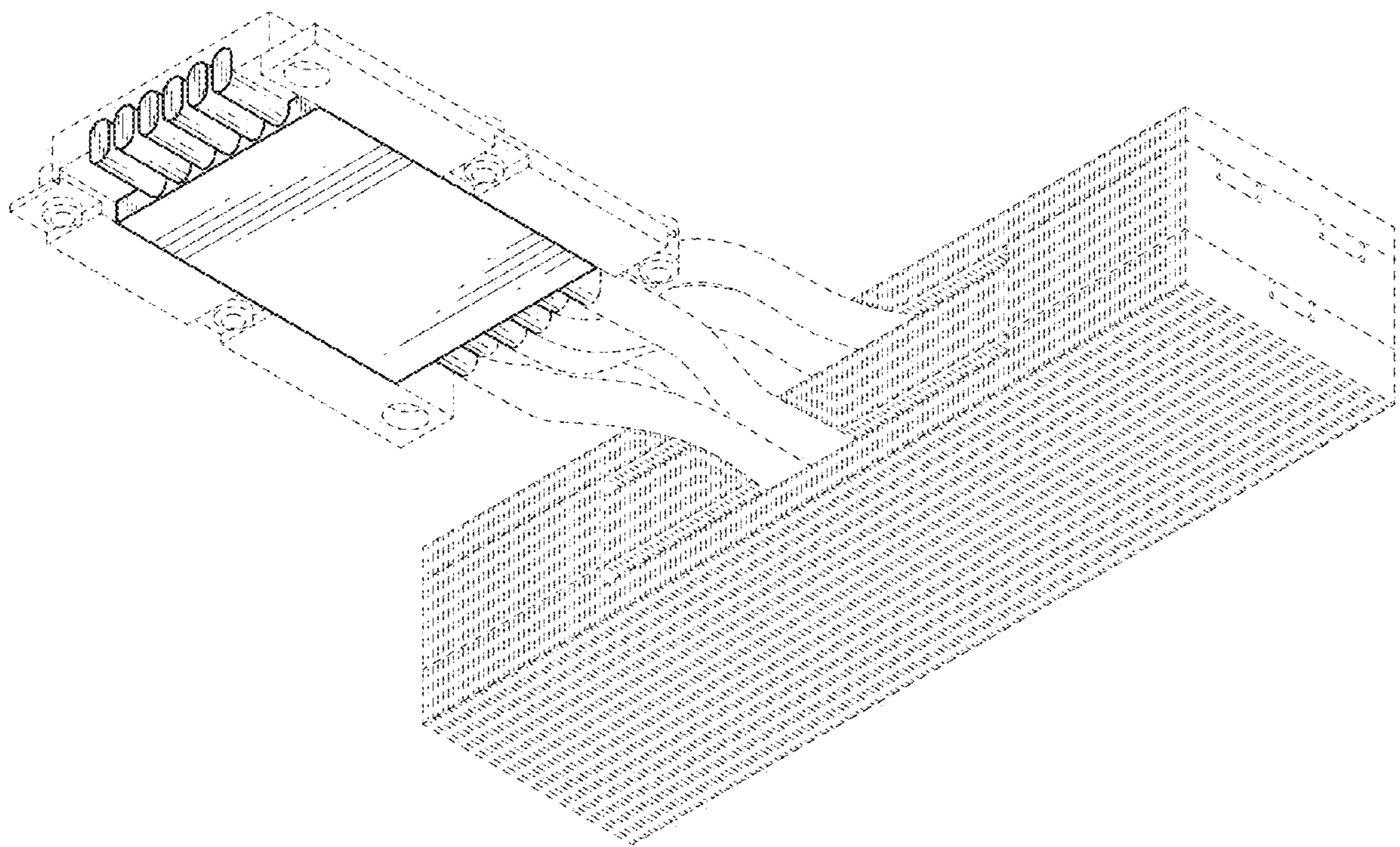


FIG. 2

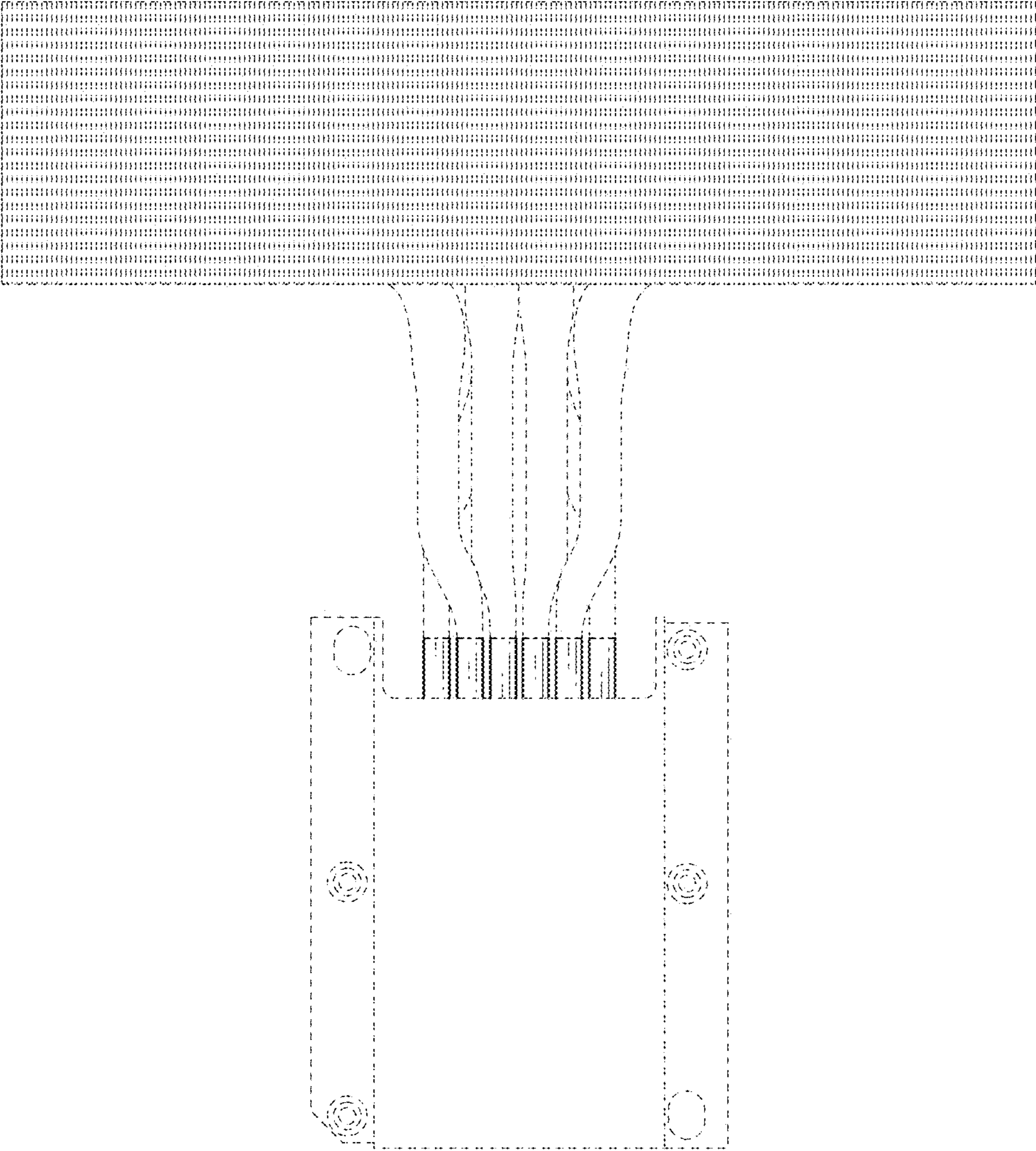


FIG. 3

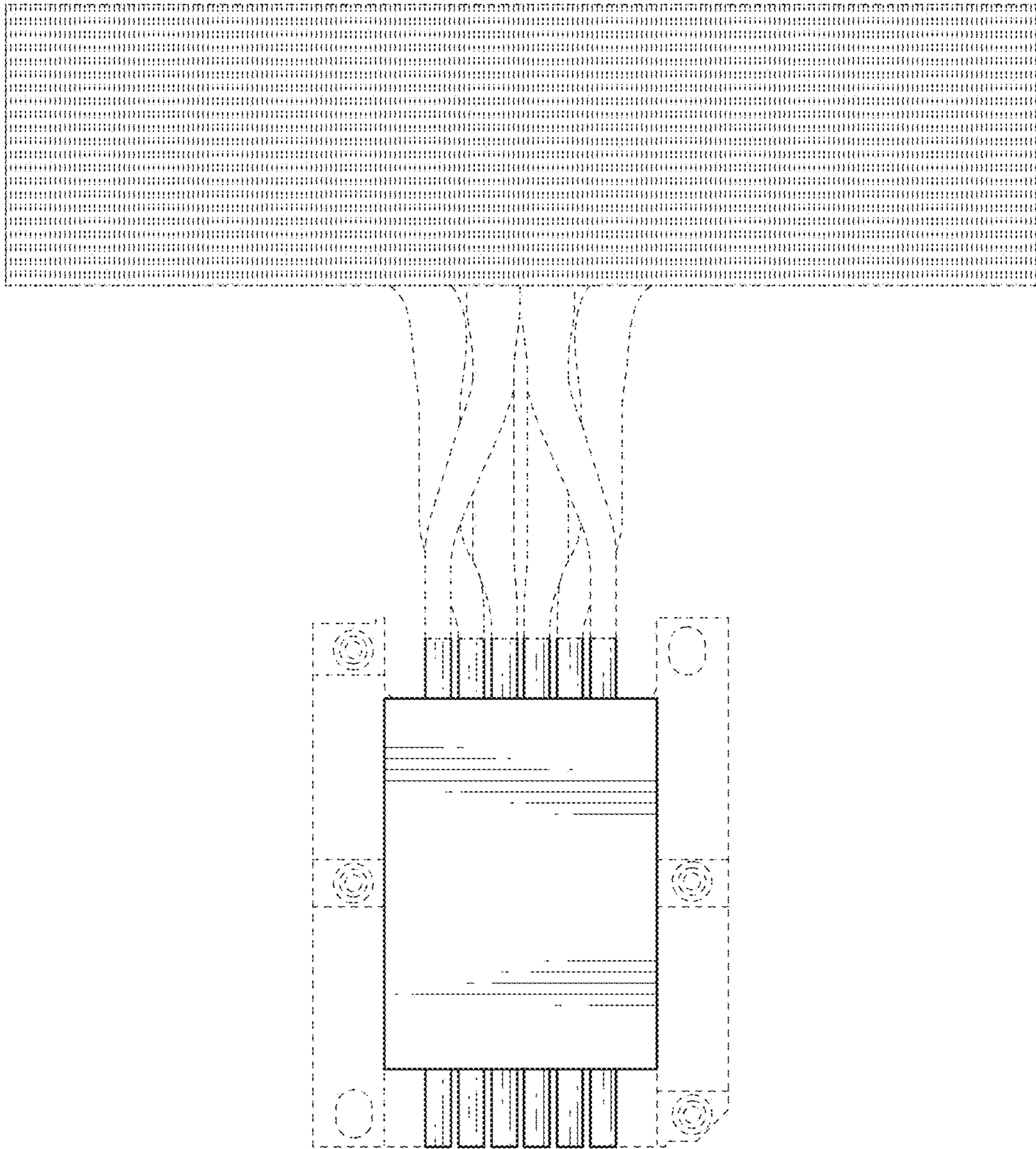


FIG. 4

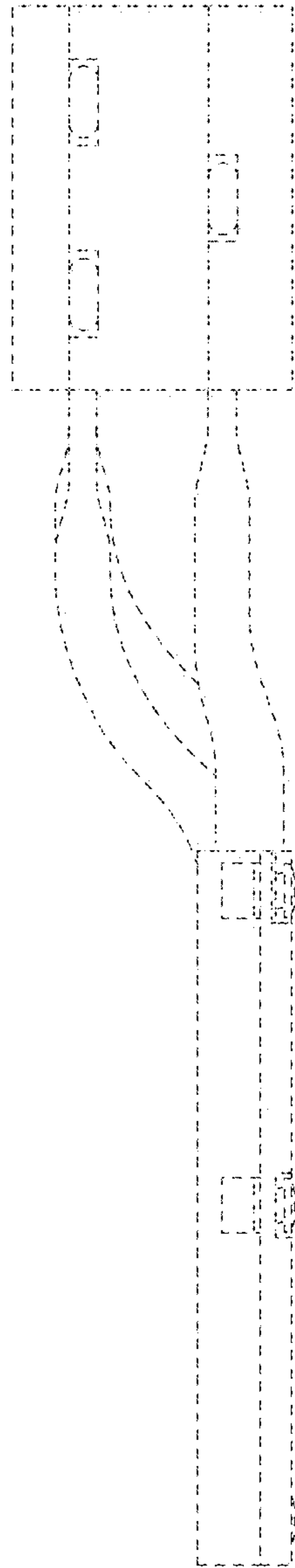


FIG. 5

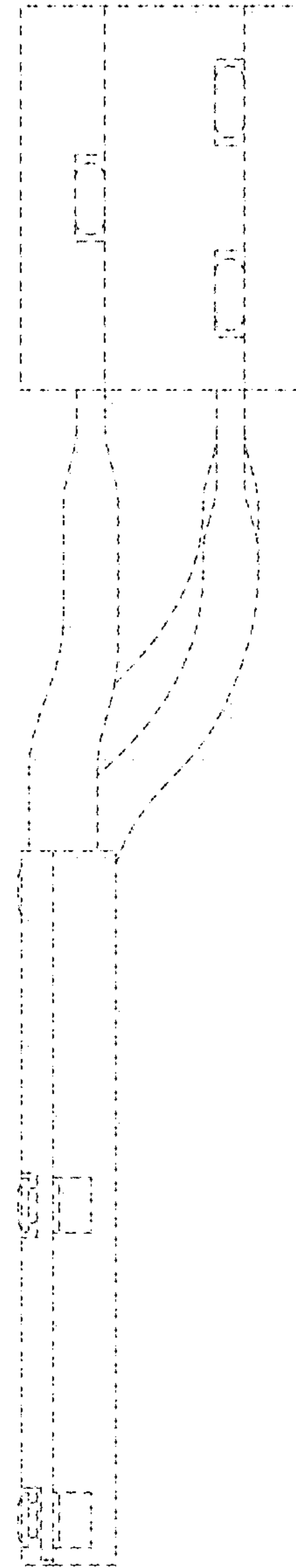


FIG. 6

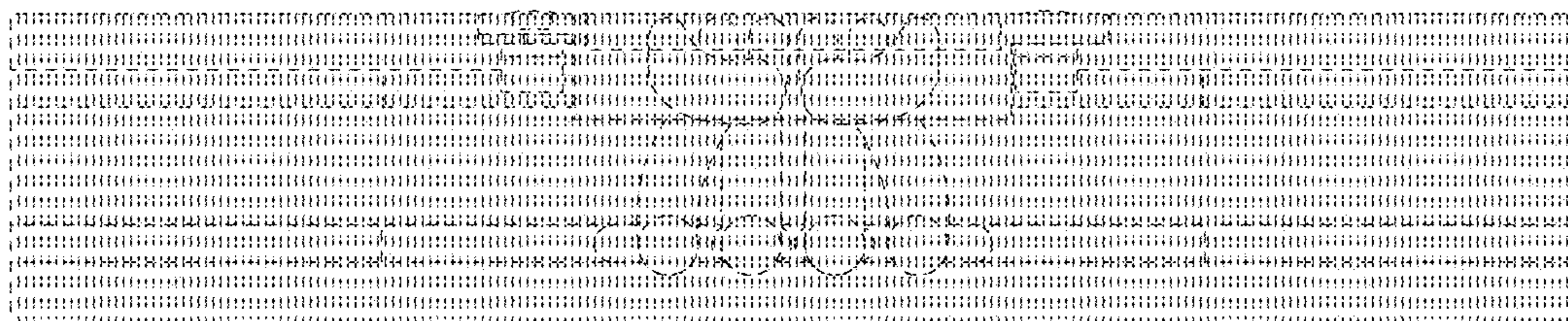


FIG. 7

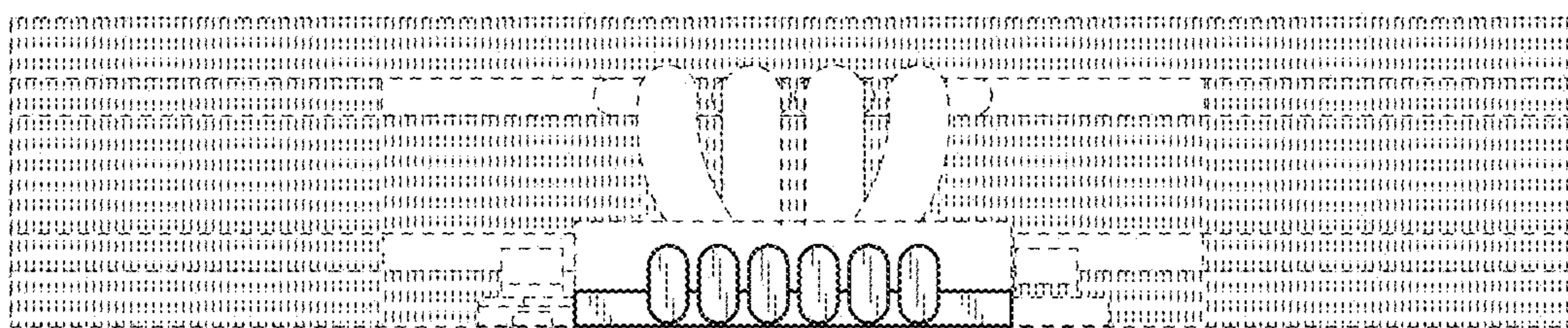


FIG. 8